

ABSTRACT OF THE DISCLOSURE

In a method of transferring semiconductor chips from a substantially flat wafer having an active side with a plurality of individual semiconductor chips formed thereon and a support side opposite the active side to a receiver, and
5 the wafer is attached with its support side by way of an adhesive sheet to a support structure and is cut into segments corresponding to the individual semiconductor chips so that the semiconductor chips are individually supported on the adhesive sheet with their active sides exposed and facing
10 away from the adhesive sheet, the support structure is moved with the individual semiconductor chips into a position wherein a particular semiconductor chip to be removed is positioned in a removal location above a receiver and the adhesive sheet is pushed downwardly at the particular semiconductor
15 chip location so as to release the particular semiconductor chip and transfer it with the active side thereof onto the receiver.